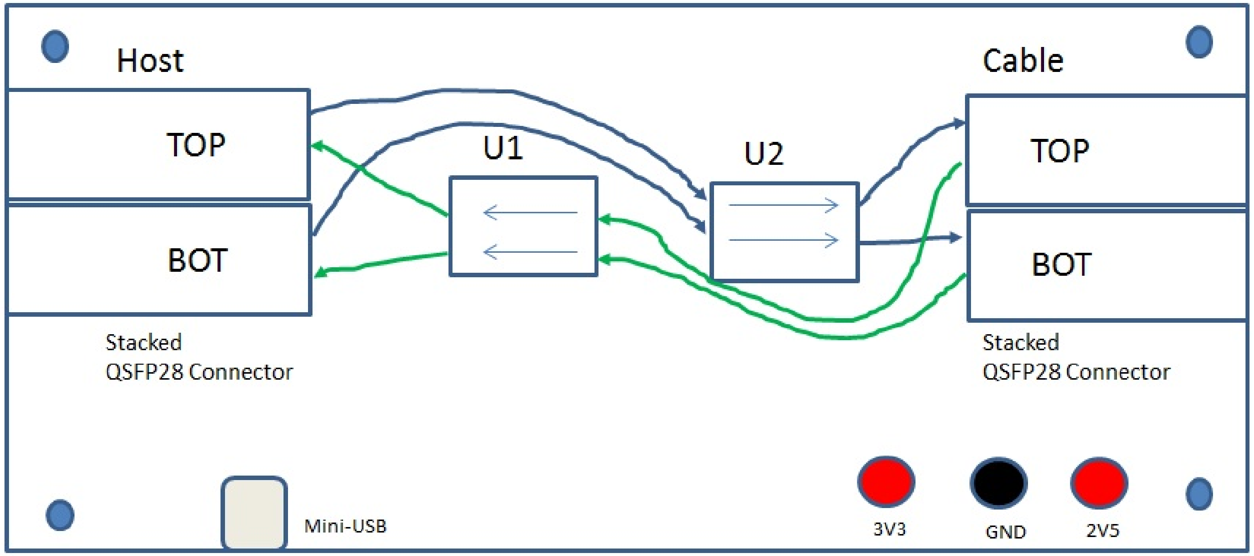
DS280BR810 QSFP Reference Design



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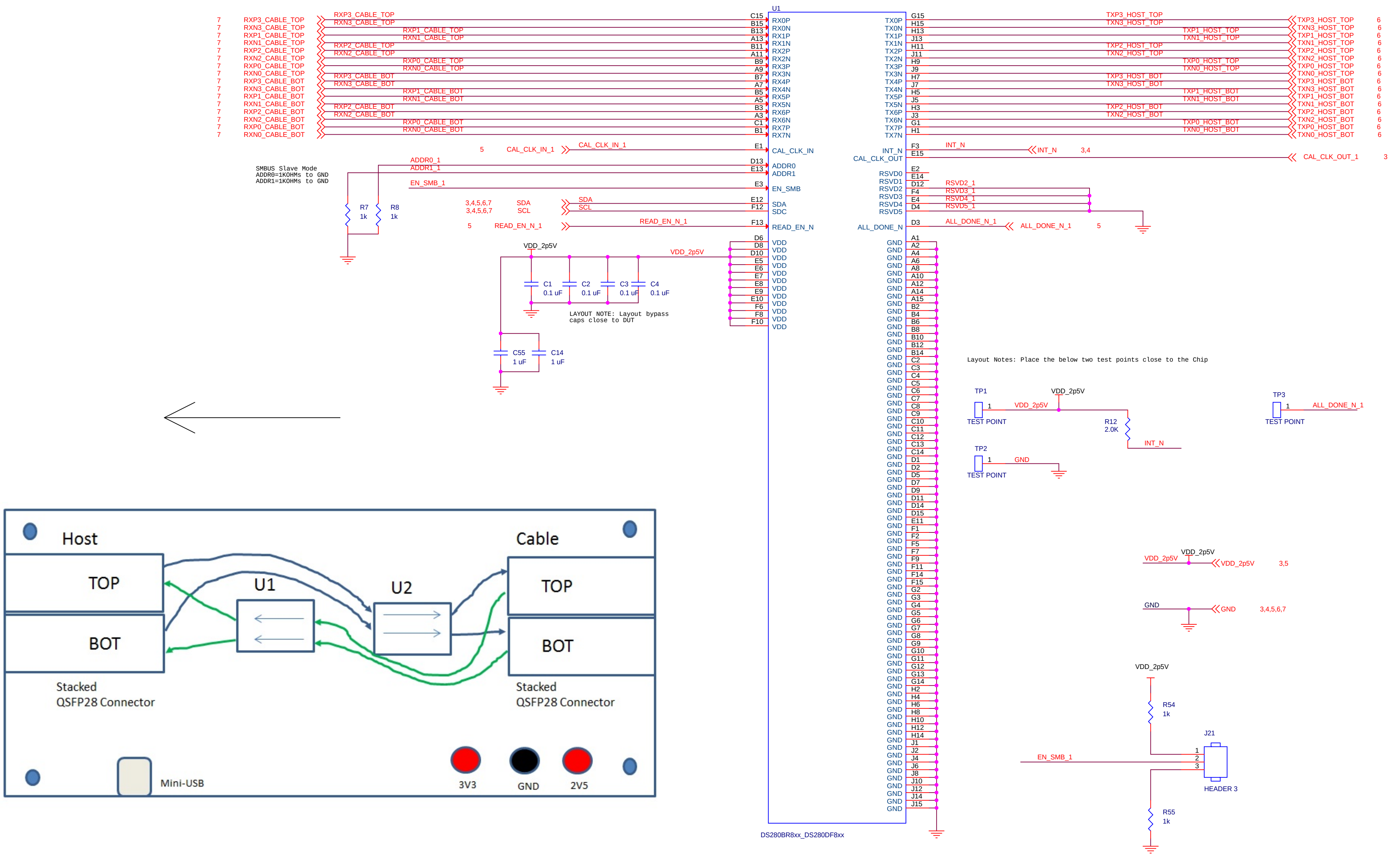
1st DS280BR810

Layout: All differential traces are to be routed with 100 ohm differential impedance



SMBUS Slave Mode
ADDR0=1KOHMs to GND
ADDR1=1KOHMs to GND

LAYOUT NOTE: Layout bypass caps close to DUT

Layout Notes: Place the below two test points close to the Chip

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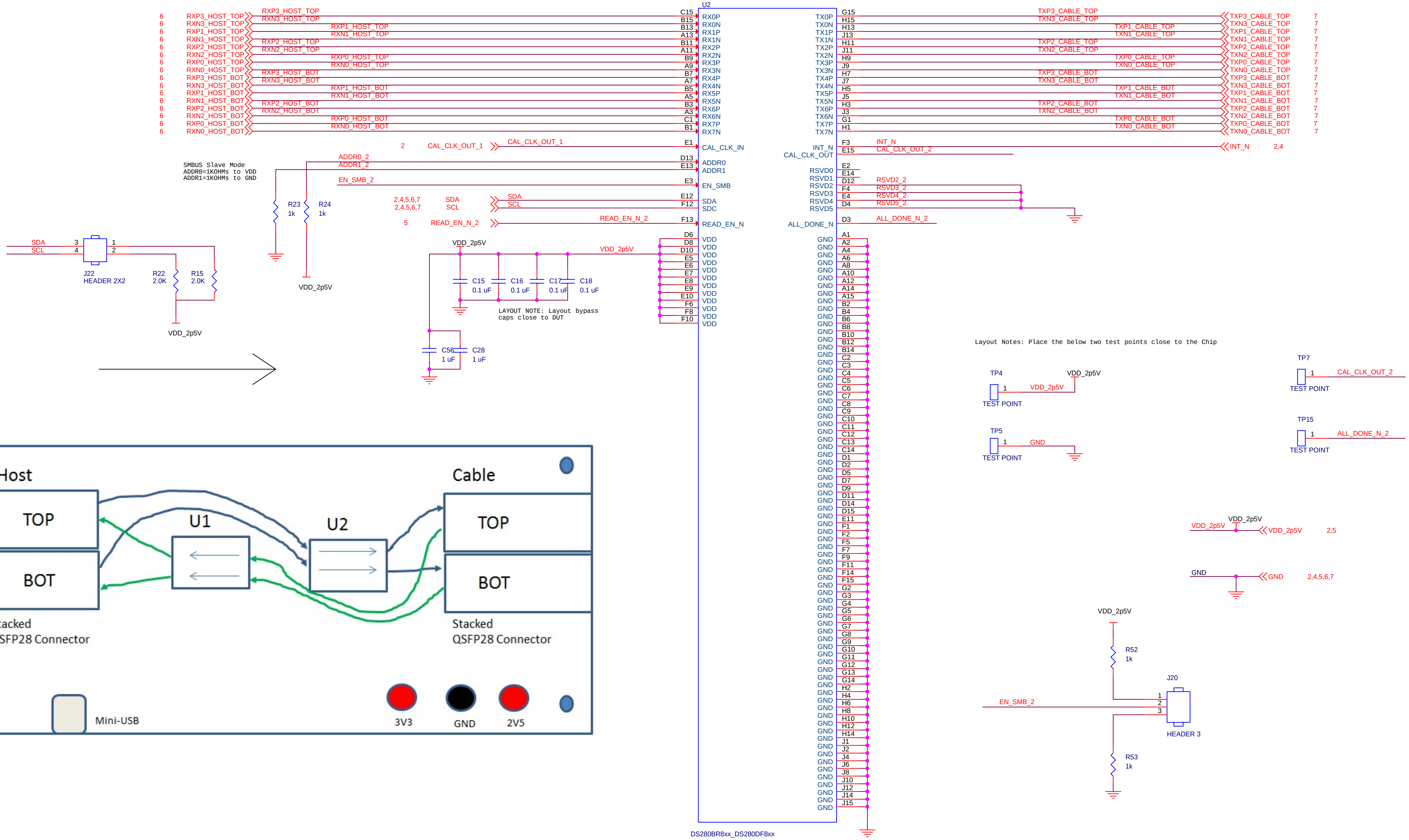
2nd DS280BR810

Layout: All differential traces are to be routed with 100 ohm differential impedance



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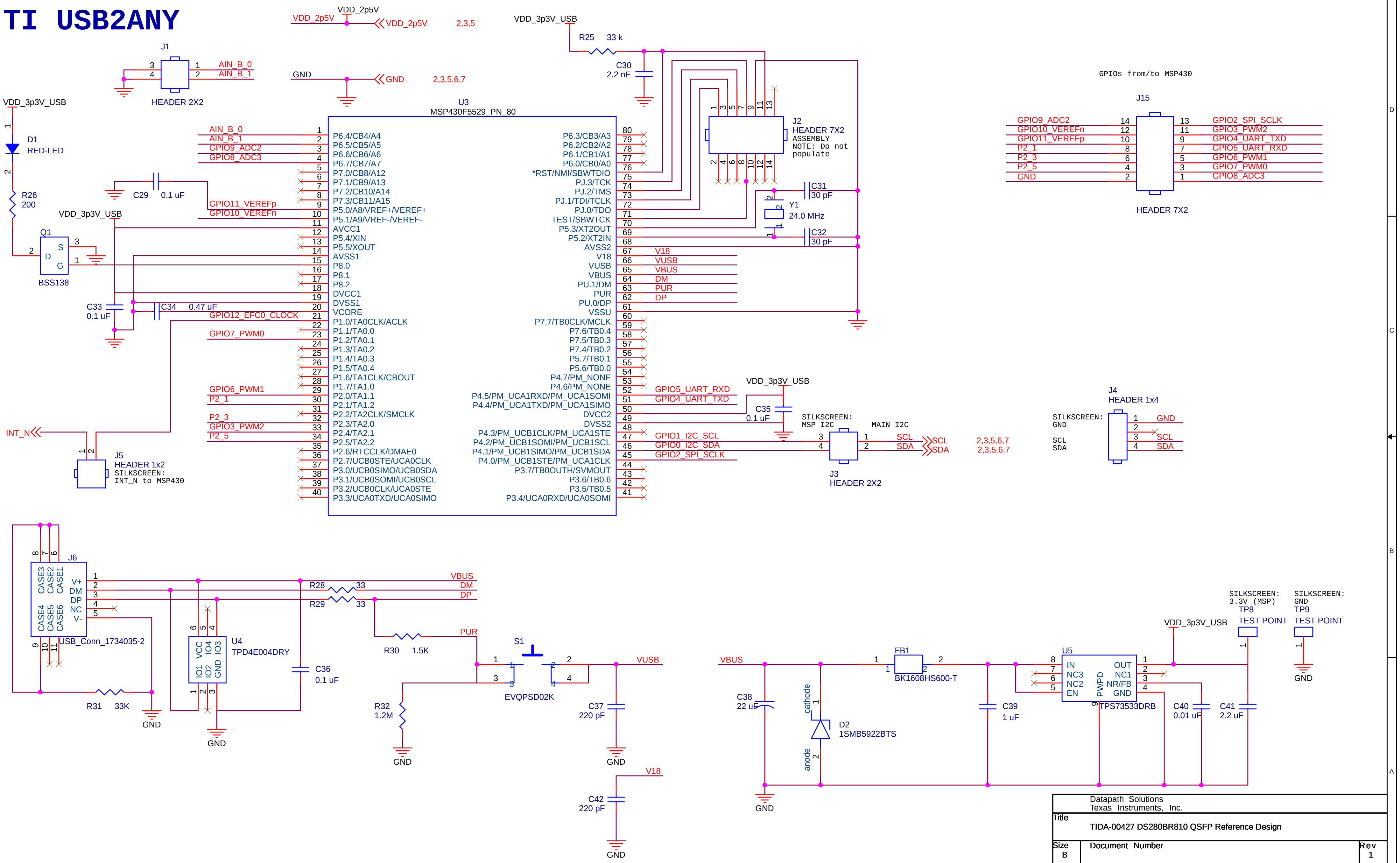
TI USB2ANY



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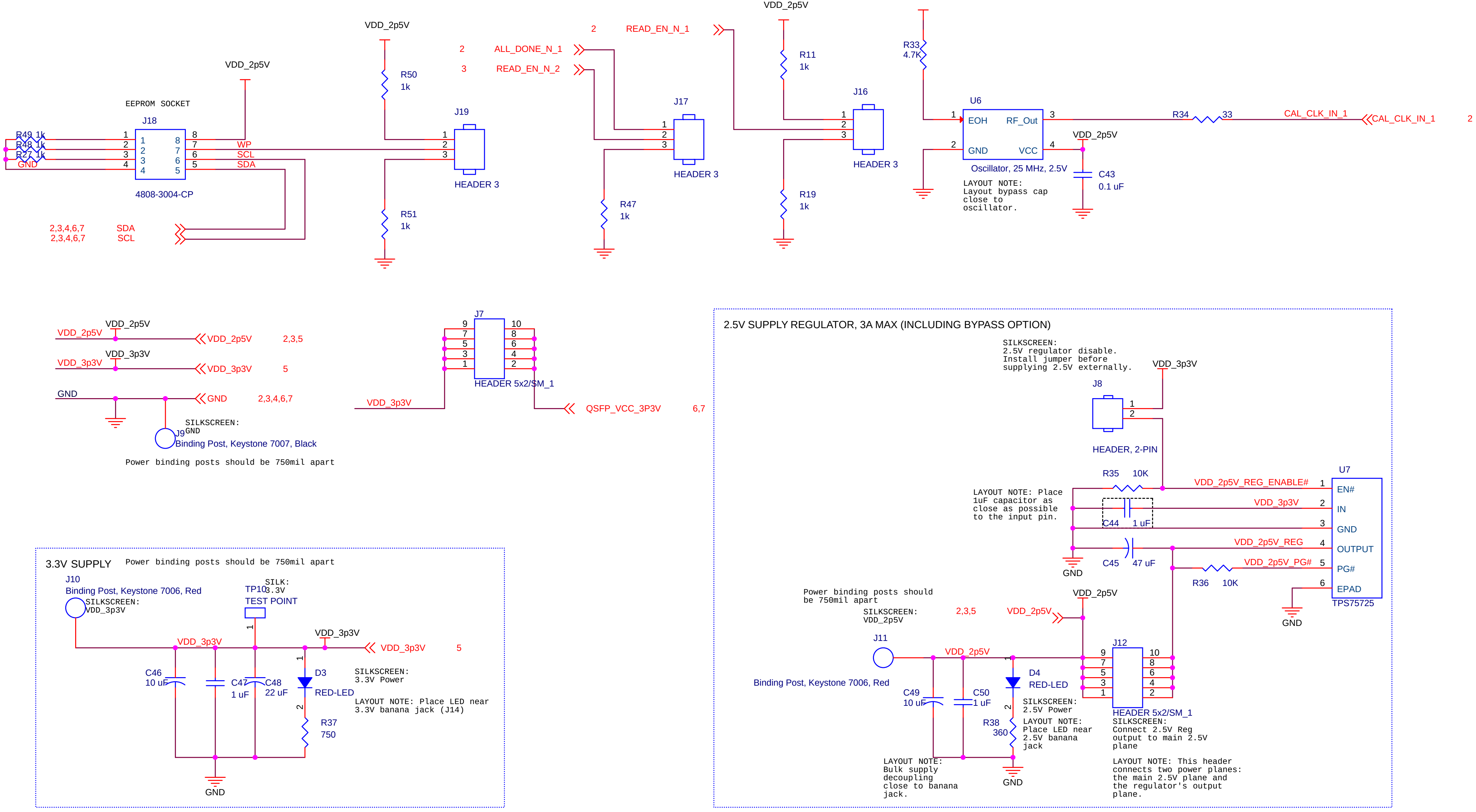
CLOCK AND POWER



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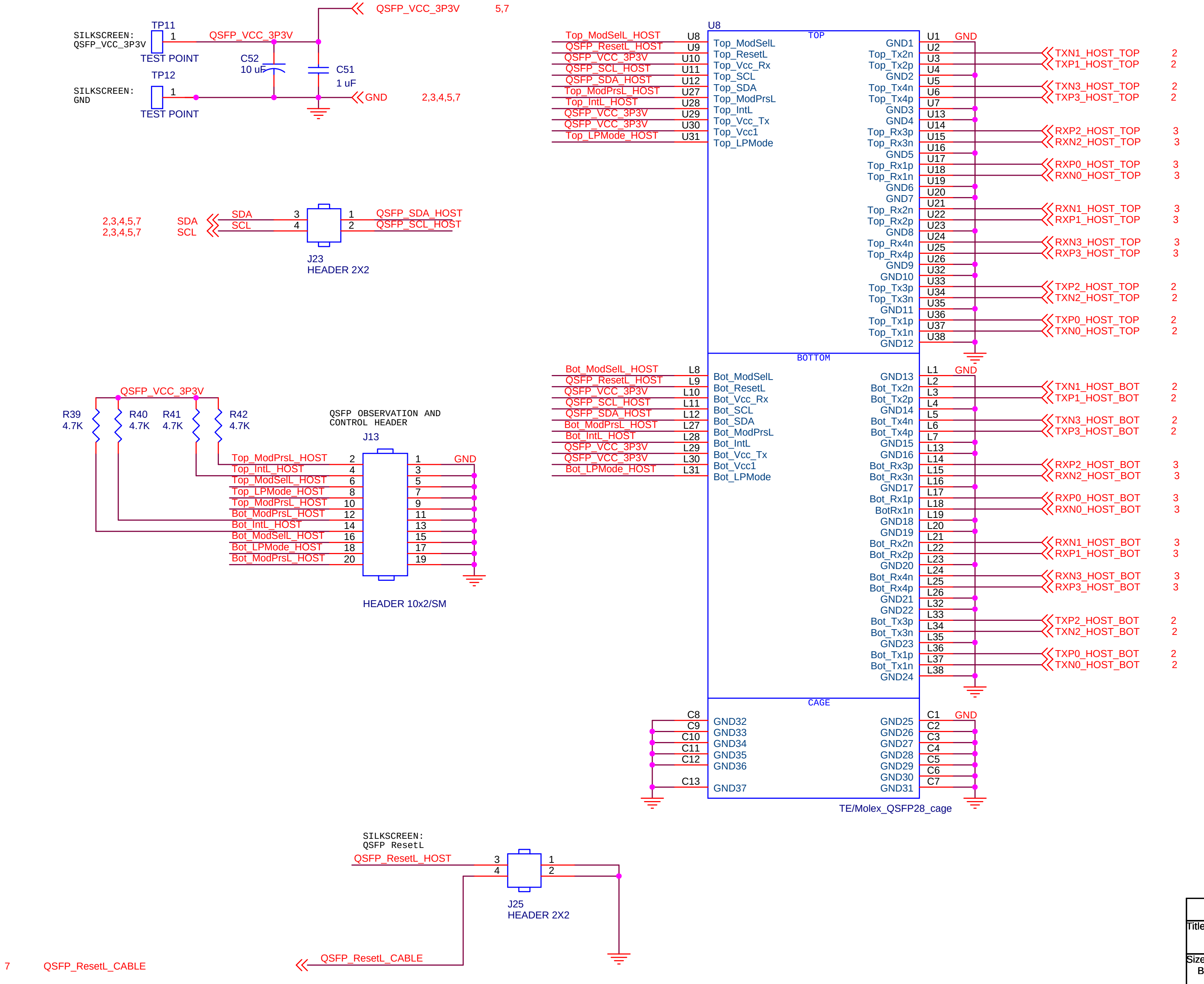
QSFP28 HOST SIDE



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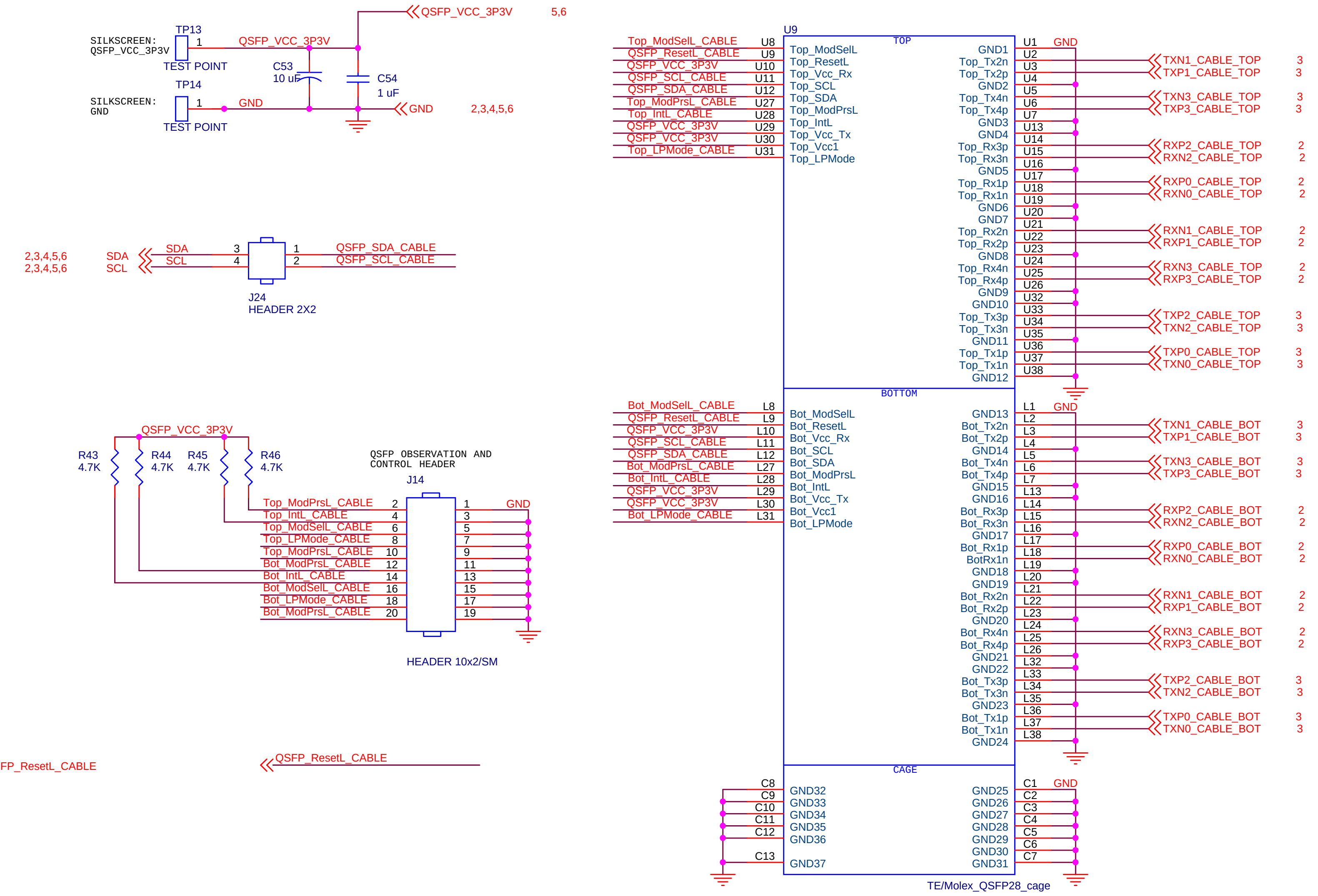
QSFP28 Cable SIDE



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